

L Number	Hits	Search Text	DB	Time stamp
1	358176	particle with size	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 15:22
2	20126	filler same (particle with size)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 15:22
3	7527	( filler same (particle with size)) same (percent weight)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 15:24
4	1729	(( filler same (particle with size)) same (percent weight)) and (board wiring carrier board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 15:25
5	1410	(( ( filler same (particle with size)) same (percent weight)) and (board wiring carrier board)) and (viscosity shear rate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 15:26
6	1168	(thermoplastic embed\$5 (thermo adj plastic) resin) and ((( filler same (particle with size)) same (percent weight)) and (board wiring carrier board)) and (viscosity shear rate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 15:28
7	1965	(curing cur\$4) with (accelerator and (acid with anhydride))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 15:33
8	29	((thermoplastic embed\$5 (thermo adj plastic) resin) and ((( filler same (particle with size)) same (percent weight)) and (board wiring carrier board)) and (viscosity shear rate))) and (curing cur\$4) with (accelerator and (acid with anhydride))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 15:33
9	29	((thermoplastic embed\$5 (thermo adj plastic) resin) and ((( filler same (particle with size)) same (percent weight)) and (board wiring carrier board)) and (viscosity shear rate))) and ((curing cur\$4) with (accelerator and (acid with anhydride)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 15:34
10	29	((thermoplastic embed\$5 (thermo adj plastic) resin) and ((( filler same (particle with size)) same (percent weight)) and (board wiring carrier board)) and (viscosity shear rate))) and ((curing cur\$4) with (accelerator and (acid with anhydride)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/26 15:34

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